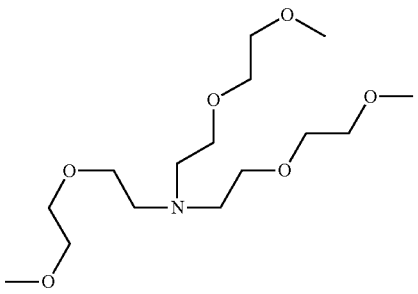
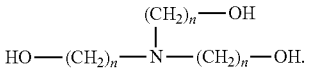
(18)



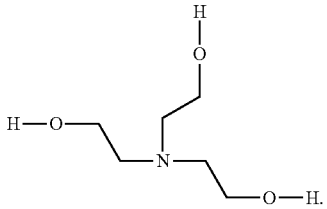
[0114] In another embodiment of any of the above aspects of this invention said solid component e), said quencher system consists only of a compound or a mixture of compounds, having a boiling point of at least 100° C. at 1 atmosphere pressure, having structure (19), wherein where n and n' are independently 2 to 4.

(19)



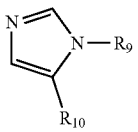
[0115] In another embodiment of any of the above aspects of this invention said solid component e), said quencher system consists only of a compound having structure (20).

(20)



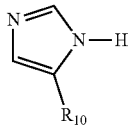
[0116] In another embodiment of any of the above aspects of this invention said solid component e), said quencher system consists only of a compound or a mixture of compounds, having a boiling point of at least 100° C. at 1 atmosphere pressure, having structure (21), wherein R_9 and R_{10} are independently selected from H, or a C-2-C25 alkyl and further wherein at least one of R9 or R10 is a C2-C25 alkyl.

(21)



[0117] In another embodiment of any of the above aspects of this invention said solid component e), said quencher system consists only of a compound or a mixture of compounds, having a boiling point of at least 100° C. at 1 atmosphere pressure, having structure (22), wherein R10 is a C2-C25 alkyl.

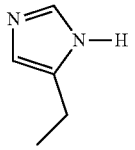
(22)



[0118] In another embodiment of the above aspects of this invention said solid component e), said quencher system, where the quencher has a boiling point of at least 100° C. at 1 atmosphere pressure, is one having one compound of structure (1), wherein R_1 is a C2 to C20 alkyl moiety, and R_{1a} is a C1 to C5 alkyl, and further wherein position 3 and 2 are connected by a double bond.

[0119] In another embodiment of any of the above aspects of this invention said solid component e), said quencher system consists only of a compound having structure (23).

(23)



[0120] In the above described novel composition the solid components may be dissolved in a solvent component f) which is an organic solvent. Examples of suitable organic solvents include, without limitation, butyl acetate, amyl acetate, cyclohexyl acetate, 3-methoxybutyl acetate, methyl ethyl ketone, methyl amyl ketone, cyclohexanone, cyclopentanone, ethyl-3-ethoxy propanoate, methyl-3-ethoxy propanoate, methyl-3-methoxy propanoate, methyl acetoacetate, ethyl acetoacetate, diacetone alcohol, methyl pivalate, ethyl pivalate, propylene glycol monomethyl ether, propylene glycol monoethyl ether, propylene glycol monomethyl ether propanoate, propylene glycol monoethyl ether propanoate, ethylene glycol monomethyl ether, ethylene glycol monoethyl ether, diethylene glycol monomethyl ether, diethylene glycol monoethyl ether, 3-methyl-3-methoxybutanol, N-methylpyrrolidone, dimethyl sulfoxide, gamma-butyrolactone, propylene glycol methyl ether acetate, propylene glycol ethyl ether acetate, propylene glycol propyl ether acetate, methyl lactate, ethyl lactate, propyl lactate, tetramethylene sulfone, propylene glycol dimethyl ether, dipropylene glycol dimethyl ether, ethylene glycol dimethyl ether or diethylene glycol dimethyl ether, gamma butyrolactone. These solvents may be used singly or in a mixture of two or more.

[0121] In one embodiment, the solid components are dissolved in PGMEA (1-Methoxy-2-propanyl acetate).

[0122] Other optional additives, which have compatibility with and can be added to the novel photoresist composition disclosed and claimed herein according to need, include auxiliary resins, plasticizers, surface leveling agents and stabilizers to improve the properties of the resist layer, and the like. Surface leveling agents may include surfactants.